

CE-25-01

JUN 22 2001

7/11/01  
JUL 11 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Perez, Erasmo; Roman, David T.  
Assignee: Amkor Technology, Inc.  
Title: Semiconductor Package With Exposed Die Pad And Body-Locking Leadframe  
Serial No.: 09/436,158 Filing Date: November 9, 1999  
Examiner: N. Ha Group Art Unit: 2814  
Docket No.: M-7744 US

RECEIVED  
TECHNICAL  
JUL 11 2001

Newport Beach, California  
June 22, 2001

Attn: Official Draftsperson  
COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

**SUBMISSION OF FORMAL DRAWINGS**


Dear Sir:

Applicant(s) submit(s) five (5) sheets of formal drawings, consisting of Figures 1, 2, 3, 4, 5, 6, 7, 8, and 9, in the above-named application. If there are any questions regarding these drawings, please call the undersigned at (949) 718-5200.

EXPRESS MAIL LABEL NO:

EL922456410US

Respectfully submitted,

  
Don C. Lawrence  
Attorney for Applicant(s)  
Reg. No. 31,975

Serial No. 09/436,158